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ABSTRACT OF THE DISCLOSURE

An improvement of the yield of semiconductor devices is achieved in the manufacture of a semiconductor device. The method includes forming a resin enclosure for block-molding a plurality of semiconductor chips by placing a plurality of semiconductor chips inside a cavity of a molding die along with a substrate, and then injecting a resin from a first side to a second side of a main surface of the substrate. The plurality of semiconductor chips are mounted on the main surface of the substrate from the first side to the second side of the main surface with a predetermined spacing, the second side facing the first side. The method is characterized by the application of cleaning treatment to the main surface of the substrate before forming the resin enclosure.